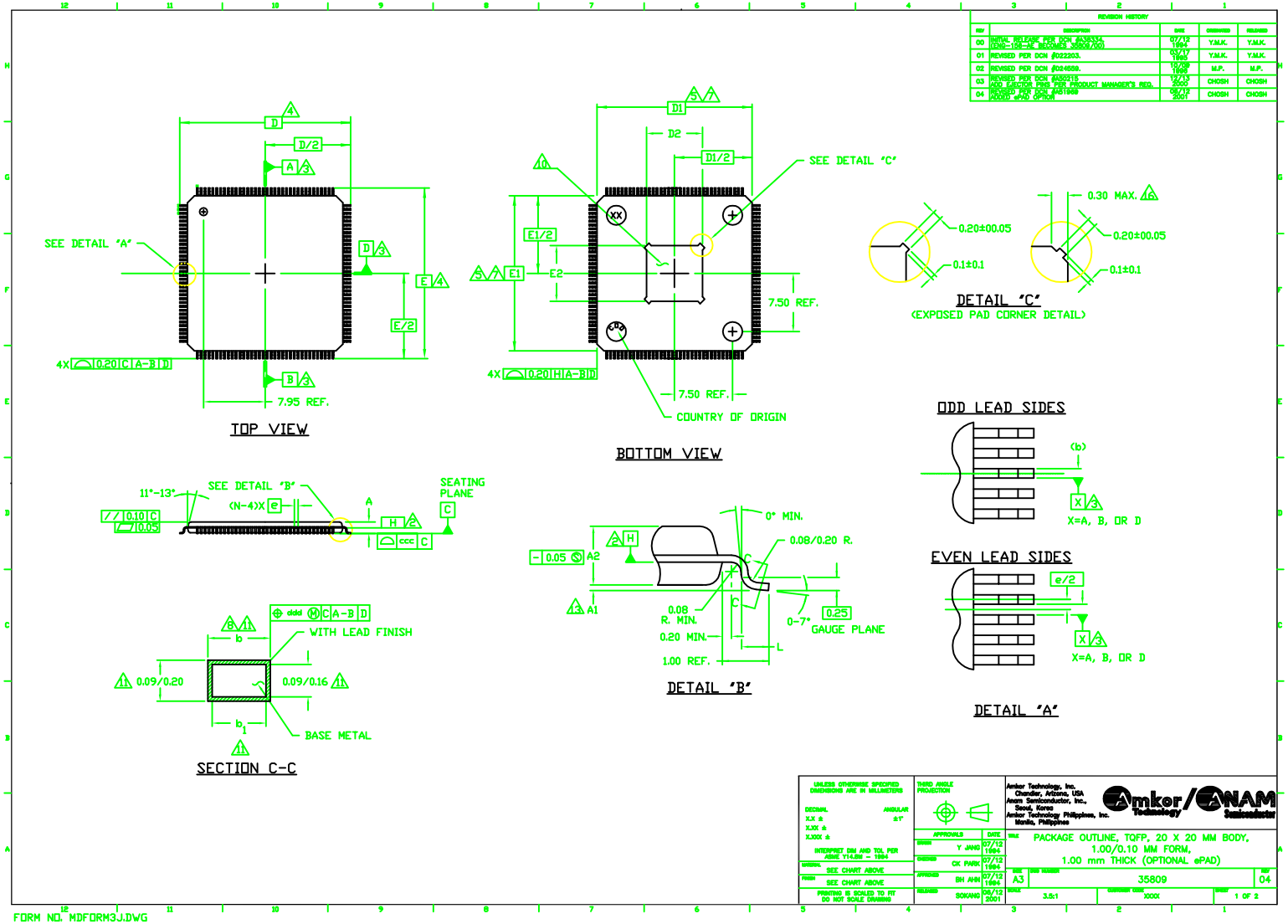
REVISION HISTORY
REV | DESCRIPTION | DATE | DRAWN | CHECKED
00 | INITIAL RELEASE PER DCN #A30902. (PKG=-115-1K, MOLDING_ID=0007.000) | 07/12 1994 | Y.M.K. | Y.M.K.
01 | REVISED PER DCN #022203. | 05/17 1995 | Y.M.K. | Y.M.K.
02 | REVISED PER DCN #034659. | 10/08 1998 | M.P. | M.P.
03 | REVISED PER DCN #A50215 ADD LEADFRAME DIMS PER PRODUCT MANAGER'S REQ. | 12/13 2000 | CHOSH | CHOSH
04 | REVISED PER DCN #071808 ADDED ePAD OPTION | 06/12 2001 | CHOSH | CHOSH
SEE DETAIL 'A'
4X 0.20|C|A-B|D
7.95 REF.
TOP VIEW
SEE DETAIL 'C'
7.50 REF.
COUNTRY OF ORIGIN
4X 0.20|H|A-B|D
BOTTOM VIEW
0.20±00.05
0.1±0.1
0.30 MAX.
DETAIL 'C'
(EXPOSED PAD CORNER DETAIL)
11°-13°
SEE DETAIL 'B'
(N-4)X e
SEATING PLANE
0.10|C
0.05
ccc C
0° MIN.
0.08/0.20 R.
0.05
A2
A1
0.08 R. MIN.
0.20 MIN.
1.00 REF.
0-7°
0.25
GAUGE PLANE
DETAIL 'B'
ODD LEAD SIDES
(b)
X=A, B, OR D
EVEN LEAD SIDES
e/2
X=A, B, OR D
DETAIL 'A'
WITH LEAD FINISH
0.09/0.20
0.09/0.16
BASE METAL
SECTION C-C
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
THIRD ANGLE PROJECTION
Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines
PACKAGE OUTLINE, TQFP, 20 X 20 MM BODY, 1.00/0.10 MM FORM, 1.00 mm THICK (OPTIONAL ePAD)
SIZE A3
DWG NUMBER 35809
REV 04
SCALE 3.5:1
CUSTOMER DWG 1000X
SHEET 1 OF 2
FORM NO. MDFORM3J.DWG